

## ABSTRACT

Provided is a copper paste for pressure bonding, the copper paste at least containing two or more copper powders having different shapes and/or particle sizes and a solvent. The copper paste has a viscosity of 10 Pa·s or more and 200 Pa·s or less. The ratio of the total mass of the two or more copper powders to the mass of the copper paste, A, is 0.60 or more and less than 0.82. When the index of bulkiness, H, is defined as  $H = C/(A \times B)$ , H is 0.75 or more and 1.00 or less, wherein A is as defined above, B represents the film thickness of a coating film formed by applying the copper paste to a substrate, and C represents the film thickness of a dried coating film formed by drying the coating film in an air atmosphere at 110°C for 20 minutes.